

### **General Description**

The 840004-11 is a 4 output LVCMOS/LVTTL Synthesizer optimized to generate Ethernet reference clock frequencies and is a member of the family of high performance clock solutions from IDT. Using a 25MHz, 18pF parallel resonant crystal, 125MHz and 62.5MHz can be generated based on one frequency select pin (F\_SEL). The 840004-11 uses IDT's 3<sup>rd</sup> generation low phase noise VCO technology and can achieve 1ps or lower typical random rms phase jitter, easily meeting Ethernet jitter requirements. The 840004-11 is packaged in a small 20-pin TSSOP package.

#### **Features**

- Four single-ended LVCMOS/LVTTL outputs 17Ω typical output impedance
- · Crystal oscillator interface
- Input frequency range: 22.4MHz to 28MHz
- Output frequency range: 56MHz 140MHz
- VCO range: 560MHz 700MHz
- RMS phase jitter at 125MHz (1.875MHz 20MHz): 0.70ps (typical)

#### Phase Noise:

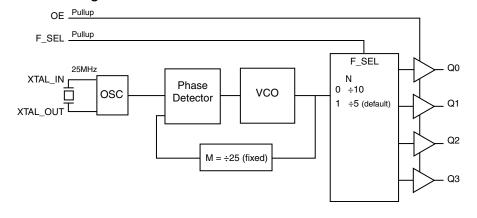
Noise Power
-95.5 dBc/Hz
-123.6 dBc/Hz
-132.8 dBc/Hz
-133.4 dBc/Hz

- Full 3.3V output supply mode
- 0°C to 70°C ambient operating temperature
- Available in lead-free (RoHS 6) package

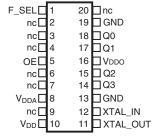
#### **Frequency Select Function Table for Ethernet Frequencies**

Inputs			
F_SEL	M Divider Value	N Divider Value	Output Frequency (MHz), 25MHz Reference
0	25	10	62.5
1	25	5	125 (default)

### **Block Diagram**



### Pin Assignment



#### ICS840004-01

20-Lead TSSOP 6.5mm x 4.4mm x 0.925mm package body G Package Top View



## **Table 1. Pin Descriptions**

Number	Name	Туре		Description
1	F_SEL	Input	Pullup	Frequency select pin. LVCMOS/LVTTL interface levels.
2, 3, 4, 6, 7, 9, 20	nc	Unused		No connect.
5	OE	Input	Pullup	Output enable pin. When HIGH, the outputs are active. When LOW, the outputs are in a high impedance state. LVCMOS/LVTTL interface levels.
8	$V_{DDA}$	Power		Analog supply pin.
10	$V_{DD}$	Power		Core supply pin.
11, 12	XTAL_OUT, XTAL_IN	Input		Crystal oscillator interface. XTAL_IN is the input. XTAL_OUT is the output.
13, 19	GND	Power		Power supply ground.
14, 15, 17, 18	Q3, Q2, Q1, Q0	Output		Single-ended clock outputs. 17 $\Omega$ typical output impedance. LVCMOS/ LVTTL interface levels.
16	$V_{DDO}$	Power		Output supply pin.

NOTE: Pullup refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

### **Table 2. Pin Characteristics**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{DD} = V_{DDO} = 3.465V$		8		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>OUT</sub>	Output Impedance			17		Ω



### **Absolute Maximum Ratings**

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V <sub>DD</sub>	4.6V
Inputs, V <sub>I</sub>	-0.5V to V <sub>DD</sub> + 0.5V
Outputs, V <sub>O</sub>	-0.5V to V <sub>DDO</sub> + 0.5V
Package Thermal Impedance, $\theta_{JA}$	73.2°C/W (0 lfpm)
Storage Temperature, T <sub>STG</sub>	-65°C to 150°C

#### **DC Electrical Characteristics**

Table 3A. Power Supply DC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{DDA}$	Analog Supply Voltage		3.135	3.3	3.465	V
$V_{DDO}$	Output Supply Voltage		3.135	3.3	3.465	V
I <sub>DD</sub>	Power Supply Current				100	mA
I <sub>DDA</sub>	Analog Supply Current				12	mA
I <sub>DDO</sub>	Output Supply Current	No Load			10	mA

Table 3B. LVCMOS/LVTTL DC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = 0$ °C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage			2		V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage			-0.3		0.8	V
I <sub>IH</sub>	Input High Current	OE, F_SEL	$V_{DD} = V_{IN} = 3.465V$			5	μΑ
I <sub>IL</sub>	Input Low Current	OE, F_SEL	$V_{DD} = 3.465V, V_{IN} = 0V$	-150			μΑ
V <sub>OH</sub>	Output High Voltage	; NOTE 1	$V_{DDO} = 3.3V \pm 5\%$	2.6			V
V <sub>OL</sub>	Output Low Voltage;	NOTE 1	$V_{DDO} = 3.3V \pm 5\%$			0.5	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DDO}/2$ . See Parameter Measurement Information section. Load Test Circuit diagram.

#### **Table 4. Crystal Characteristics**

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation			Fundamenta	ıl	
Frequency			25		MHz
Equivalent Series Resistance (ESR)				50	Ω
Shunt Capacitance				7	pF
Drive Level				1	mW

NOTE: Characterized using an 18pF parallel resonant crystal.



#### **AC Electrical Characteristics**

Table 5. AC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f	Output Frequency	F_SEL = 1	112		140	MHz
f <sub>out</sub>	Output Frequency	F_SEL = 0	56		70	MHz
tsk(o)	Output Skew: NOTE 1, 2				80	ps
RMS Phase Jitt	RMS Phase Jitter (Random);	125MHz, Integration Range: 1.875MHz – 20MHz		0.70		ps
ijit(Ø)	tjit(Ø) NOTE 3	62.5MHz, Integration Range: 1.875MHz – 20MHz		0.54		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	200		700	ps
	Output Duty Cycle	F_SEL = 0	48		52	%
odc	Output Duty Cycle	F_SEL = 1	46		54	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

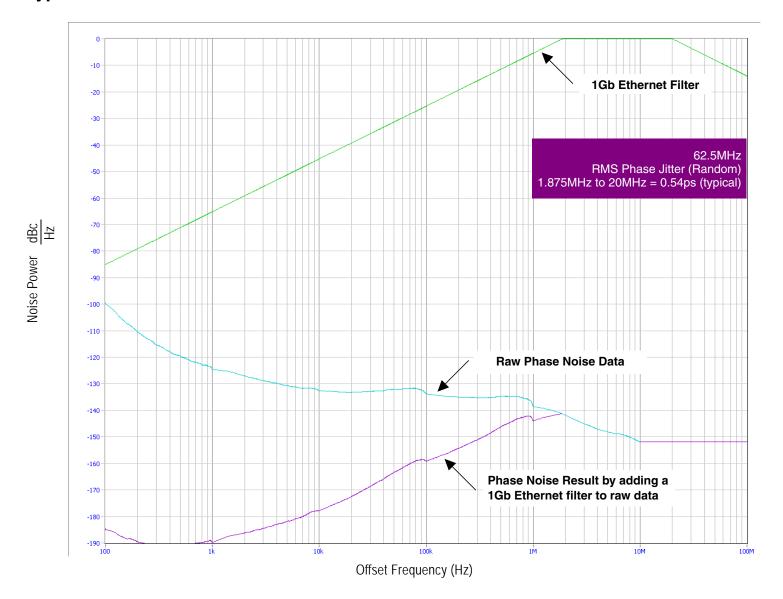
NOTE 1: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDO</sub>/2.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Please refer to the Phase Noise Plots.

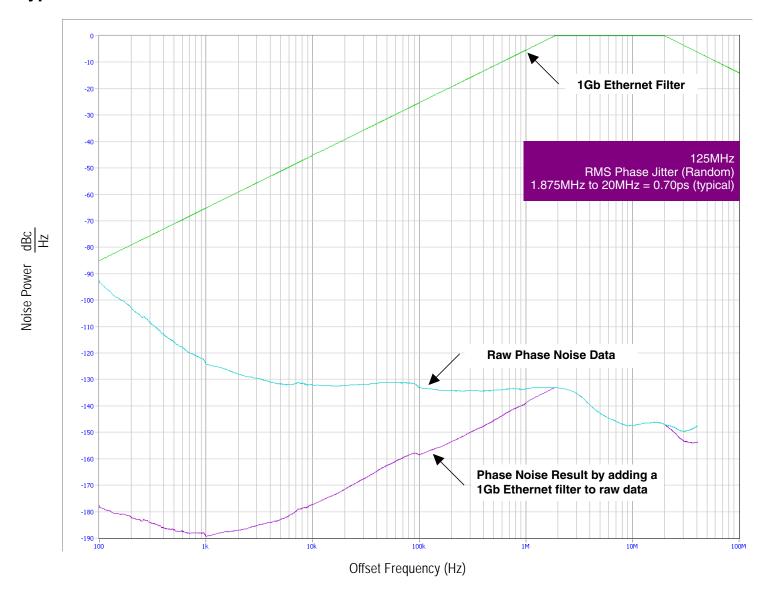


## **Typical Phase Noise at 62.5MHz**



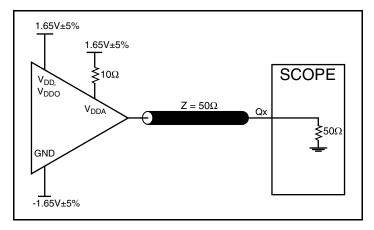


## Typical Phase Noise at 125MHz

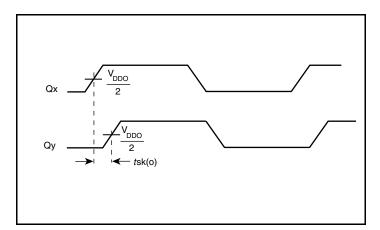




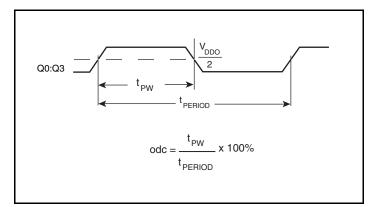
### **Parameter Measurement Information**



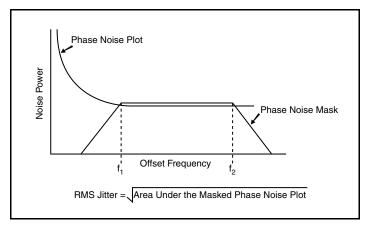
3.3V Core/3.3V LVCMOS Output Load AC Test Circuit



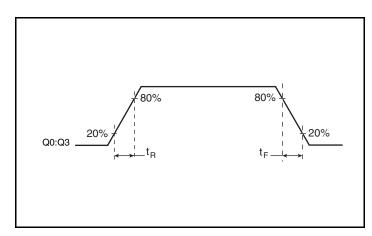
**Output Skew** 



**Output Duty Cycle Pulse Width/Period** 



**RMS Phase Jitter** 



**Output Rise/Fall Time** 



### **Application Information**

#### **Recommendations for Unused Input and Output Pins**

#### Inputs:

#### **LVCMOS Control Pins**

All control pins have internal pullups; additional resistance is not required but can be added for additional protection. A  $1k\Omega$  resistor can be used.

#### **Outputs:**

#### **LVCMOS Outputs**

All unused LVCMOS outputs can be left floating. We recommend that there is no trace attached.

#### **Power Supply Filtering Technique**

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The 840004-11 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{DD_i}$   $V_{DDA}$  and  $V_{DDO}$  should be individually connected to the power supply plane through vias, and  $0.01\mu F$  bypass capacitors should be used for each pin. Figure 1 illustrates this for a generic  $V_{DD}$  pin and also shows that  $V_{DDA}$  requires that an additional  $10\Omega$  resistor along with a  $10\mu F$  bypass capacitor be connected to the  $V_{DDA}$  pin.

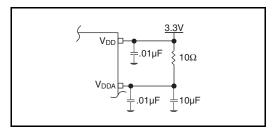


Figure 1. Power Supply Filtering



#### **Crystal Input Interface**

The 840004-11 has been characterized with 18pF parallel resonant crystals. The capacitor values shown in *Figure 2* below were determined using a 25MHz, 18pF parallel resonant crystal and were chosen to minimize the ppm error.

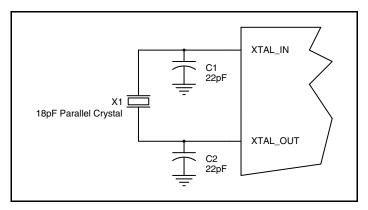


Figure 2. Crystal Input Interface

#### LVCMOS to XTAL Interface

The XTAL\_IN input can accept a single-ended LVCMOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure 3*. The XTAL\_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVCMOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output impedance of the driver (Ro) plus the series resistance (Rs) equals

the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First, R1 and R2 in parallel should equal the transmission line impedance. For most  $50\Omega$  applications, R1 and R2 can be  $100\Omega$ . This can also be accomplished by removing R1 and making R2  $50\Omega$ . By overdriving the crystal oscillator, the device will be functional, but note, the device performance is guaranteed by using a quartz crystal.

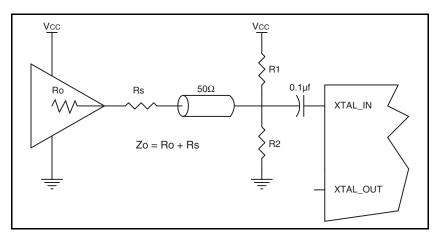


Figure 3. General Diagram for LVCMOS Driver to XTAL Input Interface



## **Reliability Information**

Table 6.  $\theta_{\text{JA}}$  vs. Air Flow Table for a 20 Lead TSSOP

$\theta_{JA}$ by Velocity					
Linear Feet per Minute	0	200	500		
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W		
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W		
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.					

#### **Transistor Count**

The transistor count for 840004-11: 1795

## **Package Outline and Package Dimensions**

Package Outline - G Suffix for 20 Lead TSSOP

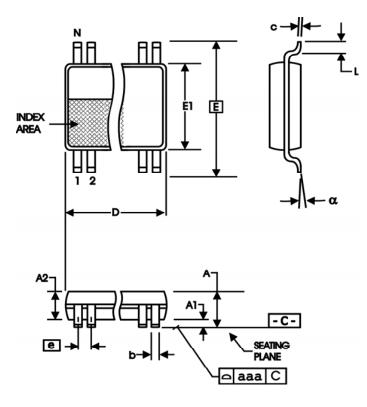


Table 7. Package Dimensions for 20 Lead TSSOP

All Dimensions in Millimeters					
Symbol	Minimum	Maximum			
N	2	0			
Α		1.20			
A1	0.05	0.15			
A2	0.80 1.05				
b	0.19	0.30			
С	0.09	0.20			
D	6.40	6.60			
Е	6.40	Basic			
E1	4.30	4.50			
е	0.65	Basic			
L	0.45	0.75			
α	0°	8°			
aaa		0.10			

Reference Document: JEDEC Publication 95, MO-153



# **Ordering Information**

## Table 8. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
840004AG-11LF	ICS40004A11L	20 Lead "Lead-Free" TSSOP	Tube	0°C to 70°C
840004AG-11LFT	ICS40004A11L	20 Lead "Lead-Free" TSSOP	Tape & Reel	0°C to 70°C



# **Revision History Sheet**

Rev	Table	Page	Description of Change	Date
А	T5	4	AC Characteristics Tables - added Thermal note.	9/16/09
		9	Added LVCMOS to XTAL Interface section.	
	Т8	11	Ordering Information Table - deleted "ICS" prefix from Part/Order Number column. Converted datasheet format.	
Α	Т8	11	Ordering Information - removed leaded devices, quantity for tape and reel and the LF note below the table.  Updated datasheet format.	12/7/15





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